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AN-9076 最新SPM[®] 2封装安装指南

安装指南

本应用笔记介绍最新SPM[®]2封装的电气间距和安装指南。

电气间距

最新SPM 2封装的电气间距规格如 表 1所示。

表 1. SPM 2封装典型电气间距

位置	电气间隙 [mm]	爬电距离 [mm]
功率端子之间	7.80	8.00
控制端子之间	3. 05	6. 85
端子与H/S之间	3.8	6. 06

安装方法和注意事项

在散热片上安装模块时,过强的不均匀紧固力会给芯片 内部施加压力,可能导致器件损坏或性能下降。图 1 显示建议紧固顺序。

表 2. 安装扭矩和散热片平面度规格

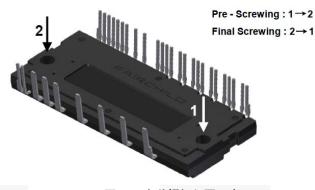


图 1. 安装螺钉紧固顺序

注意:

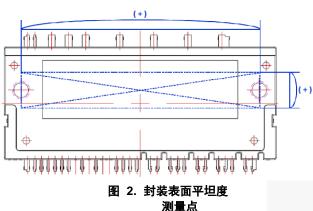
- 安装螺钉时请勿施加过大扭矩。扭矩过大可能导致陶瓷开 裂,或损坏螺钉和散热片。
- 避免只固定一侧。图 1显示安装螺钉时的建议扭矩。安装时用力不均可能会损坏陶瓷基板。预拧扭矩应设为最大 扭矩额定值的20~30%。

<u> </u>		工作条件	极限值			单位
多效	参数 工作条件		最小值	典型值	最大值	半位
器件平面度	如需相关特性,请参见图 2		0		+200	μm
散热片平面度	如需相关特性,请参见图 3		-50		+100	μm
安装扭矩 螺钉: M4	建议0.9 N m	0.9	1.0	1.5	N·m	
	建议9.1 kgf·cm	9.1	10.1	15. 1	kgf·cm	
重量				50		g

注意:

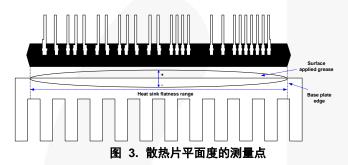
3. 建议使用螺钉组(包括弹簧/平垫圈、M4)。

AN-9076



注意:

4. 封装表面的平坦度测量点位于封装中心和四个外角。



为了得到最好的散热效果,需要尽可能扩大接触区域, 这样才能把接触热阻降到最低。

在模块和散热片之间的接触表面上正确使用导热硅膏。 防止接触表面腐蚀也非常重要。另外,确保所用的硅膏 质量稳定,可以在较宽的工作温度范围中长时间使用。

相关资源

FNA41012A, FNA42512A⁽⁵⁾, FNA42512A⁽⁵⁾ - 1200-V Motion SPM 2系列

AN-9075 - 1200-V Motion SPM 2系列用户指南

AN-9079 - 1200-V Motion SPM 2系列热性能与安装扭矩

注意:

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导热组合

 在模块基板或散热片上使用厚度至少为150 µm的导 热硅膏。

使用扳手将螺钉紧固至额定扭矩。超出扭矩的最大限值

紧固模块时在安装模块的边缘会看到有一圈导热膏。

紧固顺序

- 以低于1.0 N·m的扭矩固定所有螺钉(用手拧或使用 螺丝刀)
- 交叉的施加1.5~2.5 N m的冲击扭矩
- 使用推荐的螺钉组(包括弹簧/平垫圈M4)



图 4. 螺钉组 (尺寸M4、弹簧垫圈7.0Φ、平垫圈9.0Φ)

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